

EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	38	(semiconductor near5 polishing).ti. and (ohta. in. or itai.in.)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/01/21 16:34
S2	55	pasqualoni.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/01/21 16:50
S3	9	pasqualoni.in. and fumed near silica	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/01/21 16:50
S4	13471	tamai.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/01/21 16:51
S5	1	tamai.in. and silica and bulk near density	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/01/21 16:51
S6	6256	kaufman.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/01/21 16:52
S7	20	kaufman.in. and fumed near silica and complexing near agent	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/01/21 16:53
S8	4	(semiconductor near2 polishing).ab. and fumed near silica same density and (acid or acidic) and alkali	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/01/22 08:36
S9	3	(semiconductor near2 polishing).ab. and fumed near silica same bulk near density	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/01/22 08:37
S10	2	("20020033382").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2010/01/22 13:08

S11	0	S10 and characteristic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/01/22 13:08
S12	1492	423/335.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/01/22 13:51
S13	6345	51/307-309.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/01/22 13:51
S14	1124	106/3.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/01/22 13:51
S15	3847	438/692-693.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/01/22 13:51
S16	0	(S12 S13 S14 S15) and semiconductor.ab. and fumed near silica same2 bulk near density and particle near3 size	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/01/22 13:52
S17	1	(S12 S13 S14 S15) and semiconductor.ab. and fumed near silica same2 bulk near density	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/01/22 13:52
S18	3	(S12 S13 S14 S15) and (polishing or polish or CMP or chemical near mechanical).ab. and fumed near silica same2 bulk near density and particle near3 size	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/01/22 13:53
S19	2	("6248144").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2010/01/22 14:12
S20	1	S19 and acid	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/01/22 14:12
S21	2	("20030104770").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2010/01/22 14:18

S22	2	S21 and (hydroxide or ammonium)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/01/22 14:18
S23	2	("20040159050").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2010/01/22 15:49
S24	0	S23 and bulk near3 density	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/01/22 15:55
S25	1	S23 and density	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/01/22 15:55
S26	1	S23 and (ammonium or hydroxide)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/01/22 15:58
S27	0	(polishing or planarizing or planarization or CMP). ti. and (nm or nanometer) with (better or optimiz\$3 or increas\$4 or decreas\$4 or maximize or flaws or scratch\$4) with abrasvie and (fumed near silica or fume near silica)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/01/22 16:30
S28	0	(polishing or planarizing or planarization or CMP). ti. and (nm or nanometer) with (better or optimiz\$3 or increas\$4 or decreas\$4 or maximize or flaws or scratch\$4) with abrasive and (fumed near silica or fume near silica)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/01/22 16:34
S29	60	(polishing or planarizing or planarization or CMP). ti. and (nm or nanometer) with (better or optimiz\$3 or increas\$4 or decreas\$4 or maximize or flaws or scratch\$4) with abrasive and (fumed near silica or fume near silica)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2010/01/22 16:34

S30	2	("20040127047").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2010/01/22 16:34
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1/ 22/ 2010 5:08:14 PM

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 \ 10594475_semiconductor polishing composition.wsp**